International Workshop on Integrated Power Packaging (IWIPP 2022)

Registration is now open for IWIPP 2022, a PSMA and IEEE sponsored hybrid workshop, will be held August 24-26, 2022, at the World Trade Center in Grenoble, France, and hosted by G2Elab. IWIPP is a growing and successful power technology workshop with excellent speakers and networking opportunities.

Under the leadership of General Chairman Dr. Francesco Iannuzzo, Professor, Aalborg University, IWIPP brings together industry, academic and government researchers in the field of power electronics components, electrical insulating materials, and packaging technologies to facilitate and promote the development and commercialization of high-density and high-efficiency power converters. Invited presentations and contributed papers will address a range of topics, including power module design, magnetic and dielectric materials technology, component performance, and application-level impacts of packaging technology. Presenters will address important challenges and present solutions to increase reliability and manufacturability while targeting improved performance with reduced size and system cost.

Technical Chairman Nick Baker, University of Alabama invites you to this year's outstanding technical program which includes an exciting set of power technology and packaging Keynote addresses including:

- **"Packaging, Integration and Fast switching: what has been achieved and what´s next?" - *Eckart Hoene, Chief Expert Power Electronics, Fraunhofer IZM, Germany***
    - *Only close interaction between packaging end circuit engineers will bring power electronics to the next step. This presentation will give an overview on achievements in packaging and its implementation into commercial products as well as new concepts intended to reduce the technological market barrier.*
- **"Environmental Trends and Challenges on Power Packaging" - *Garron Morris and Chris Genthe, Senior Principal Engineer, Rockwell Automation, USA***
    - *This keynote covers the challenges of increasing power densities, coupled with new environmental stresses stemming from changing customer locations, behaviours, and applications.*
- **Insulation Materials and Systems for Power Electronic Modules: Challenges and Future Research Needs, *Mona Ghassemi, Assistant Professor, Virginia Tech, USA***
    - *This presentation critically reviews recent research on electrical insulation materials and systems used in power electronics devices and focuses on electrical treeing in silicone gel, PD modelling, and mitigation methods. In particular, it shows that the investigations carried out to date are in their infancy regarding the working conditions targeted for next-generation WBG power devices.*

Packaging and related technologies are the key to creating high-density power sources. Attendance at this important workshop can keep you and your colleagues on the cutting edge. Registration is now open for this important event at Registration – IWIPP. If your company would benefit from

meeting the attendees, registration is also available for event partners and exhibitors. The event is available for both **in person** and **virtual** attendance. Additional information regarding the workshop can be found at the conference website: https://iwipp.org/ .

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